

ABSTRACT OF THE DISCLOSURE

A solid-state image pickup device in which no warp occurs in a solid-state image pickup element chip is provided. A solid-state image pickup device, including
5 a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, a wiring substrate electrically connected to the solid-state image pickup element chip and adapted to transmit signals from each one of a plurality of
10 solid-state image pickup elements, and a protection cap provided on a light incident side of the solid-state image pickup element chip and adapted to protect the solid-state image pickup element chip, is characterized in that the solid-state image pickup element chip is
15 formed on a substrate with a thermal expansion coefficient equal to that of the protection cap, and the substrate and the protection cap are sealed with a sealing resin.

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